

N° 2017-005-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Capacity extension by introduction of 300mm wafer diameter for dedicated OptiMOS™5 25V and 60V products at Infineon Villach, Austria

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **19. May 2017**.
- Infineon aligns with the widely-recognized JEDEC STANDARD“**JESD46**“, which stipulates:
“**Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
Postal Address Headquarters: Am Campeon 1-12, D-85579 Neubiberg, Phone +49 (0)89 234-0
Chairman of the Supervisory Board: Wolfgang Mayrhuber
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck
Registered Office: Neubiberg Commercial Register
Amtsgericht München HRB 126492

Product / Process Change Notification



N° 2017-005-A

► **Products affected:** See affected product list (1_cip17005_a)

► **Detailed Change Information:**

Subject:

- Introduction of 300mm wafer diameter at Infineon Technologies Austria AG.
- Interlayer dielectric form for OptiMOS™5 25V products with 300mm Silicon.
- Standardization of mould compound for TDSON-8 package
- Standardization of bond pad metallization stack

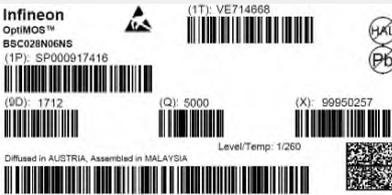
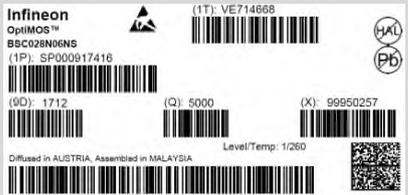
Reason:

- Next phase of Front End capacity expansion by introduction of 300mm wafer diameter to support continuous increasing customer demand in the future.
- Continuous process improvements with latest technology trends on state of the art FE production equipment and tools.

-Infineon is standardizing:

- mould compound for all of its OptiMOS™ 60V products in TDSON-8 package.
- bond pad metallization stack

to reduce complexity during the production chain

Description:	<u>Old</u>	<u>New</u>
Wafer diameter:	<ul style="list-style-type: none"> ■ Infineon Technologies Austria AG, Villach, Austria (200mm) 	<ul style="list-style-type: none"> ■ Infineon Technologies Austria AG, Villach, Austria (200mm and 300mm)
Lot number & Label:	<ul style="list-style-type: none"> ■ VFxxxxxx = 200mm production 	<ul style="list-style-type: none"> ■ VFxxxxxx = 200mm production <p>and</p> <ul style="list-style-type: none"> ■ VFxxxxxx = 300mm production 

Product / Process Change Notification



N° 2017-005-A

Standardizing mould compound TDSON-8 package:

■ Hitachi CEL 1772

■ Hitachi CEL 9240

- Standardization of source & gate pad metallization stack allows Infineon to improve quality and efficiency in the manufacturing environment by reducing complexity during the whole production chain.
- The Interlayer dielectric form follows the process based on state of the art 300mm production equipment and tools for OptiMOS™5 25V products.

► Product Identification:

Internal traceability assured via Baunumber, Lotnumber and date code

External traceability assured via Waferlot number printed on Barcode Product Label (refer to section "Lot number & Label" – page 2)

► Impact of Change:

NO change on electrical, thermal parameters and reliability as proven via product qualification and characterization.

NO change in existing datasheet parameters

NO change in quality and reliability. Processes are optimized to meet product performance according to already applied Infineon specification.

► Attachments:

1_cip17005_a Affected Product List

► Time Schedule:

- Final qualification report: Available on request
- First samples available: On request
- Intended start of delivery: 2017-06-01 or earlier pending on customer approval

If you have any questions, please do not hesitate to contact your local Sales office.

